

Ultra Low Power Wi-Fi® Solutions

Wi-Fi [®] SoC, Wi-Fi [®] Modules, Wi-Fi [®] + BLE Modules



DA16200 SoC Highly Integrated Ultra Low Power Wi-Fi System on Chip (SoC)

The DA16200 is a highly integrated ultra-low power Wi-Fi system on a chip (SoC), which contains an 802.11b/g/n radio (PHY), baseband processor, media access controller (MAC), on-chip memory, and a host networking applications processor all on a single silicon die. The SoC enables full offload capabilities, running the entire networking stack on chip, so that no external network processor, CPU, or micro-controller is required, though the SoC may optionally be used with a microcontroller.

A synthesis of breakthrough ultra low power technologies enables extremely low power operation in the SoC. Low power algorithms shut down every micro element of the chip that is not in use, which allows a near zero level of power consumption when not actively transmitting or receiving data. Such low power operation can typically deliver a year or more of battery life depending on

the application. Advanced algorithms enable staying asleep until the exact moment required to wake up to transmit or receive.

The SoC is built from the ground up for the Internet of Things. It is ideal for door locks, thermostats, security video cameras, sensors, and other devices that require Wi-Fi where battery powered operation is desirable.

Evaluation boards and a complete software development kit (SDK) are available. The SDK includes sample applications, provisioning apps, AT command library, power management tools, and more.

A fully staffed, highly trained, worldwide application engineering support team is available to help you quickly integrate the SoC or its associated module into your product.

DA16200 SOC

Features

Features	Benefits
Fully Featured AT Command set	 Ready2Go SW examples and applications Quick and easy path for fast prototyping
Ultra Low Power	 Breakthrough VirtualZero[™] technology Virtually no power consumption in sleep state Enables year-plus battery life Ultra low power sensor wake-up
Superior Range	 Industry leading output power and Rx sensitivity for max range
Highly Integrated SoC	 802.11b/g/n radio PHY, BB/MAC, PA, LNA w/ on chip SRAM Up to 72 Mbps, MCS0-7
Full Offload	SoC runs full OS & TCP/IP stack
Simple Setup & Provisioning	• Automatically find & configure new devices w/ smartphone app
Complete Software Stack	Comprehensive networking software stack
Leading Security	 Multiple layers of commercial, industrial, and banking grade security Hardware accelerated Digital certificates Elliptic curve encryption
OTA Firmware Update	Enables field deployed device firmware updates
Multiple I/Os	 UART, SPI, SDIO, ADC, I²C, PWM, I²S, GPIOs, JTAG and SWD
eMMC/SD Expanded Memory	Data logging, memory intensive applications

Block Diagram (SOC)





DA16200 Modules Full Offload Highly Integrated Ultra Low Power Wi-Fi Modules

- The fully integrated module consists of the DA16200 SoC, 4MB flash memory, RF components including crystal oscillator, RF lumped filter, and either a chip antenna or a connector for an external antenna
- Single power supply voltage (3.3V)
- 37 pins including GPIOs, JTAG, RTC control, UART, power input, and 32.768kHz crystal
- DA16200 module SKUs:
 - DA16200MOD-AAC4WA32 with on board chip antenna
 - DA16200M0D-AAE4WA32 with external antenna connector (u.FL)
- Dimensions
 - Both modules have the same dimensions
 - 13.8 mm x 22.1 mm x 3.3 mm

Module Types

On Board Chip Antenna	
13.8 mm x 22.1 mm x 3.3 mm	
DA16200MOD-AAC4WA32	



External Antenna	
Connector (u.FL)	
13.8 mm x 22.1 mm x 3.3 mm	
DA16200MOD-AAE4WA32	



Benefits
Breakthrough VirtualZero™ technology
Virtually no power consumption in sleep state Franklas year plus bettery life
Enables year-plus battery life
• Olla low power sensor wake-up
 Industry leading output power and Rx sensitivity for max range
 802.11b/g/n radio PHY, BB/MAC, PA, LNA w/ on chip SRAM
 Up to 72 Mbps, MCS0-7
SoC runs full OS & TCP/IP stack
• Automatically find & configure new devices w/ smartphone app
Comprehensive networking software stack
 Secure boot Secure debug Secure asset storage
Hardware accelerated TLS Digital certificates Elliptic curve encryption
Enables field deployed device firmware updates
 UART, SPI, SDIO, ADC, I²C, PWM, I²S, GPIOs, JTAG and SWD
Data logging, memory intensive applications

Block Diagram (SOC)





Country	On Board Chip Antenna	External Antenna Connector (u.FL)	
US FCC	2AU49-DA16200MC	2AU49-DA16200ME	
Canada IC	25650-DA16200MC	25650-DA16200ME	
	CE & RoHS	CE & RoHS	
EU GE	Compliance	Compliance	
South Karoo KC	R-C-fci-DA16200M-	R-C-fci-DA16200M-	
SUULII KUIEd KC	C4WA3	E4WA3	
Japan TELEC	201-190886	201-190892	
China SRRC	2020DP0489	2020DJ0161(M)	

DA16600 Combo Wi-Fi + BLE Modules Full Offload Highly Integrated Ultra Low Power Modules

- The DA16600 is a module solution for IoT applications featuring lowest power Wi-Fi + BLE
- The fully integrated module consists of:
 - Wi-Fi SoC: DA16200
 - BLE SoC: DA14531
- 32KHz RTC Crystal for Wi-Fi
 32MHz Crystal for BLE
- 4MB Flash memory – 40MHz Crystal for Wi-Fi
- 32101HZ Crystal for BLE
 Chip antenna or u.FL connector
- SPDT Antenna Switch
- Single power supply voltage (3.3V)

DA16600 module SKUs:

- DA16600M0D-AAC4WA32 chip antenna
- DA16600M0D-AAE4WA32 external antenna connector (u.FL)

Module Types

- **On Board Chip Antenna** 14.2 mm x 24.6 mm x 3.0 mm DA16600M0D-AAC
 - External Antenna Connector (u.FL) 14.2 mm x 24.6 mm x 3.0 mm DA16600M0D-AAE





Features	Benefits	
Low Power Wi-Fi	VirtualZero™ DA16200 SoC ● 802.11n 1x1 low power 2.4 GHz	
	• Up to 72 Mbps, MCS0-7	
Low Power BLE	SmartBond TINY [™] DA14531 SoC BT5.1 compliant BLE	
Ultra Low Power	 Enables year-plus battery life Breakthrough VirtualZero[™] low power technology 	
	 Virtually no power consumption in sleep state Ultra low power sensor wake-up 	
	 Runs on small batteries and coin cells 	
Ni-Fi/BLE Coexistence • Built in, customizable, coexistence algorithms		
Superior Range	 Wi-Fi: Industry leading output power and Rx sensitivity for max range 	
	• BLE: 4x range of BT 4.0	
Full Offload	SoC runs full OS & TCP/IP stack on module	
Simple Setup & Provisioning	 Provision Wi-Fi connection simply with BLE 	
	 Automatically find & configure new devices w/ smartphone app 	
Complete Software Stack	Comprehensive networking software stack	
Leading Security	ding Security • Secure boot • Secure debug • Secure asset storage	
	Hardware accelerated TLS Digital certificates Elliptic curve	
OTA Firmware Update	 Enables field deployed device firmware updates 	
Multiple I/Os	 UART, SPI, ADC, I²C, PWM, I²S, GPIOs, JTAG and SWD 	

System Block Diagram





Country	On Board Chip Antenna	External Antenna Connector (u.FL)	
US FCC	TBD	TBD	
Canada IC	TBD	TBD	
	CE & RoHS	CE & RoHS	
EU GE	Compliance	Compliance	
South Korea KC	TBD	TBD	
Japan TELEC	TBD	TBD	
China SRRC	TBD	TBD	

ULTRA LOW POWER WI-FI® SOLUTIONS

VirtualZero™	Leading Edge Low Power Technology		Additional Features	
> 1 Year Battery Life	zZz	 Three Sleep Modes 1. Unconnected (nanoamp) 2. Connected ultra low (microamp) 3. Connected ultra fast (microamp) Ultra Fast Wake-up Ultra Fast Return to Sleep Extends battery life 	 +20 dBm ra booster mo -100 dBm F Highly Integra + No CPU or required + Full offload + Runs network 	inge de Ax sensitivity I ted SoC MCU Drk stack
Notworking	Protocols	Complete software stack including TCP/UDP/IP, HTT	P, HTTPs, SD_MOTT_CoAP	
Capabilities	Provisioning	Included smartphone app for iOS & Android; WPS 2	0	
	Sensors	ADC: 4-channel SAR 12-bit		DA16200

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Smart Lock with Super-Low Power Wi-Fi and Bluetooth Low Energy



Portable Wi-Fi Controlled RGBW Lighting



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